Si4435FDY

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PRODUCT SUMMARY				
V _{DS} (V)	-30			
$R_{DS(on)}$ max. (Ω) at V_{GS} = -10 V	0.019			
$R_{DS(on)}$ max. (Ω) at V_GS = -4.5 V	0.030			
Q _g typ. (nC)	13.5			
I _D (A) ^a	-12.6 ^e			
Configuration	Single			

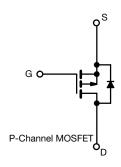
FEATURES

P-Channel 30 V (D-S) MOSFET

- TrenchFET[®] Gen III p-channel power MOSFET
- 100% R_g tested
- Material categorization:
 for definitions of compliance please see
 <u>WWW.vishay.com/doc?99912</u>
 FREE

APPLICATIONS

- Adapter switch
- Load switch
- DC/DC converters
- High speed switching
- Power management in battery-operated, mobile and wearable devices



ORDERING INFORMATION

Package	SO-8
Lead (Pb)-free and halogen-free	Si4435FDY-T1-GE3

PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	-30	V	
Gate-source voltage		V _{GS}	± 20		
Continuous drain current (T _J = 150 °C)	T _C = 25 °C		-12.6 ^e		
	T _C = 70 °C		-10 ^a		
	T _A =25 °C	I _D	-8.6 ^{b, c}		
	T _A = 70 °C		-6.9 ^{b, c}	A	
Pulsed drain current (t = 100 µs)		I _{DM}	-32 ^a		
Continuous source-drain diode current	T _C = 25 °C		-4		
	T _A = 70 °C	I _S	-1.9 ^{b, c}		
Maximum power dissipation	T _C = 25 °C		4.8		
	T _C = 70 °C		3.1		
	T _A = 25 °C	P _D	2.2 ^{b, c}	W	
	T _A = 70 °C	1	1.4 ^{b, c}		
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	**	
Soldering recommendations (peak temperature) d, e		Ť	260	°C	

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum junction-to-ambient b, d	t ≤ 10 s	R _{thJA}	45	56	°C/W	
Maximum junction-to-case (drain)	Steady state	R _{thJF}	20	26		

Notes

a. Package limited

b. Surface mounted on 1" x 1" FR4 board

c. t = 10 s

d. Maximum under steady state conditions is 100 °C/W

e. T_C = 25 °C

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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static				•	•		
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = -250 μA	-30	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$		-	-25	-		
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = -250 μA	-	4.5	-	mV/°C	
Gate-source threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250 μA	-1	-	-2.2	V	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$	-	-	± 100	nA	
Zero gate voltage drain current		$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	-	-	-1	1.	
	I _{DSS}	V _{DS} = -30 V, V _{GS} = 0 V, T _J = 55 °C	-	-	-10	μA	
On-state drain current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	-10	-	-	Α	
Drain-source on-state resistance ^a		V _{GS} = -10 V, I _D = -9 A	-	0.015	0.019	Ω	
	R _{DS(on)}	V _{GS} = -4.5 V, I _D = -7 A	-	0.023	0.030		
Forward transconductance ^a	g _{fs}	V _{DS} = -10 V, I _D = -9 A	-	25	-	S	
Dynamic ^b		· -					
Input capacitance	C _{iss}		-	1500	-	pF	
Output capacitance	C _{oss}	V_{DS} = -15 V, V_{GS} = 0 V, f = 1 MHz	-	180	-		
Reverse transfer capacitance	C _{rss}		-	150	-		
•	İ	V _{DS} = -15 V, V _{GS} = -10 V, I _D = -5 A	-	28	42	nC	
Total gate charge	Qg	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_D = -5 \text{ A}$	-	13.5	21		
Gate-source charge	Q _{gs}	$V_{DS} = -15 \text{ V}, \text{ V}_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -5 \text{ A}$	-	4.4	-		
Gate-drain charge	Q _{gd}		-	4.3	-		
Gate resistance	R _g	f = 1 MHz	0.6	3.3	6.6	Ω	
Turn-on delay time	t _{d(on)}		-	26	50	-	
Rise time	t _r	V_{DD} = -15 V, R_L = 15 Ω , $I_D \cong$ -1 A, V_{GEN} = -4.5 V, R_g = 1 Ω	-	30	60		
Turn-off delay time	t _{d(off)}		-	21	40		
Fall time	t _f		-	16	30		
Turn-on delay time	t _{d(on)}		-	9	20	- ns -	
Rise time	t _r	V _{DD} = -15 V, R _I = 15 Ω, I _D ≅ -1 A,	-	18	35		
Turn-off delay time	t _{d(off)}	$V_{\text{GEN}} = -10 \text{ V}, \text{ R}_{\text{g}} = 1 \Omega$	-	23	45		
Fall time	t _f		-	15	30		
Drain-Source Body Diode Characteristi	cs			1	1		
Continuous source-drain diode current	Is	T _C = 25 °C	-	-	-4		
Pulse diode forward current	I _{SM}		-	-	-32	- A	
Body diode voltage	V _{SD}	I _S = -5 A, V _{GS} = 0 V	-	-0.82	-1.2	V	
Body diode reverse recovery time	t _{rr}		-	20	40	ns	
Body diode reverse recovery charge	Q _{rr}		-	10	20	nC	
Reverse recovery fall time	ta	I_F = -5 A, dl/dt = 100 A/µs, T _J = 25 °C	-	10	-	ns	
Reverse recovery rise time	t _b		_	10	-		

Notes

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %

b. Guaranteed by design, not subject to production testing

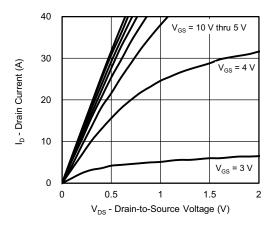
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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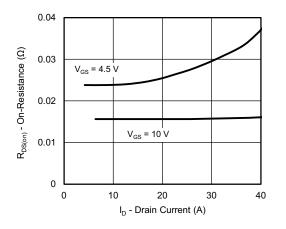


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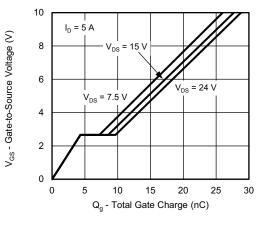
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



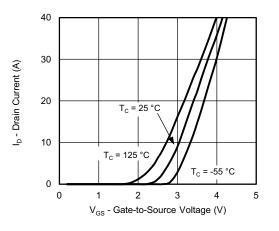
Output Characteristics



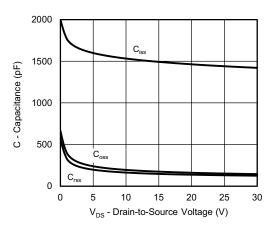
On-Resistance vs. Drain Current and Gate Voltage



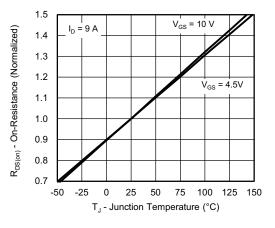
Gate Charge



Transfer Characteristics



Capacitance



On-Resistance vs. Junction Temperature

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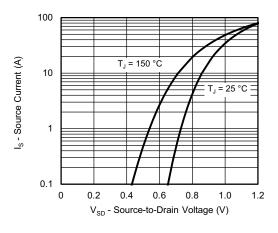
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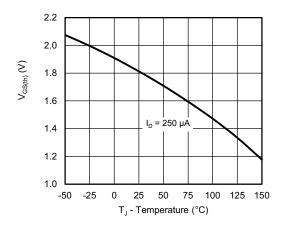


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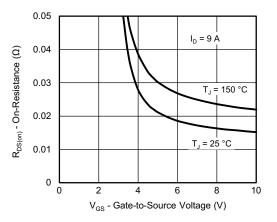
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



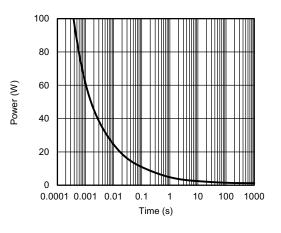
Source-Drain Diode Forward Voltage



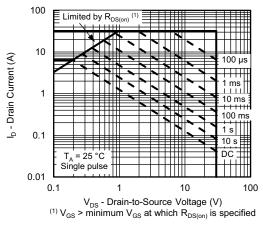
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



Safe Operating Area, Junction-to-Ambient

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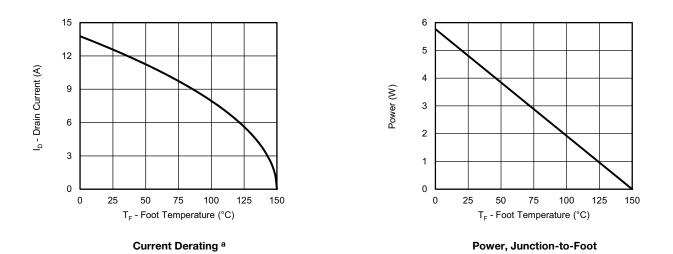
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Note

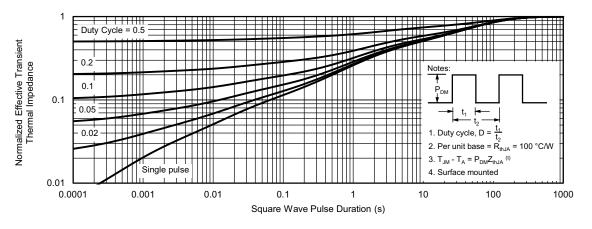
a. The power dissipation P_D is based on T_J max. = 25 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



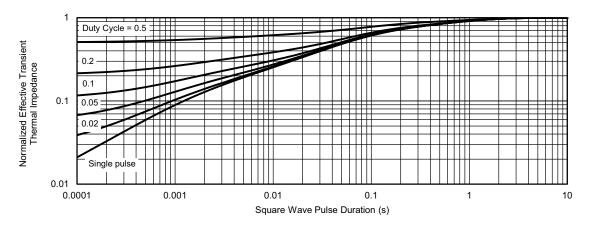
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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